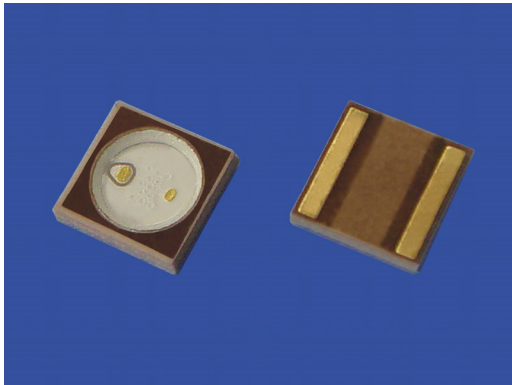


**NEW!**

## LTCC LED Package & Substrate

Ceramic Solution for **LED Flash** and **LED Backlight Unit**

### Product

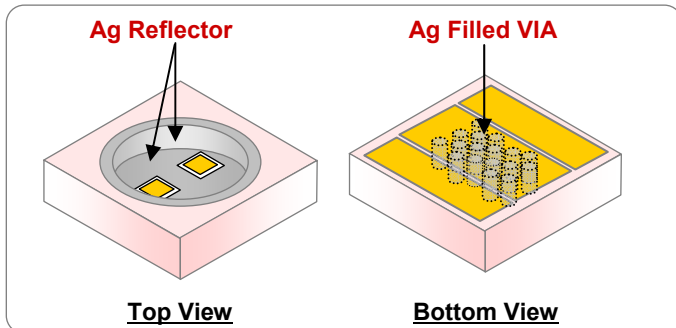


### Features

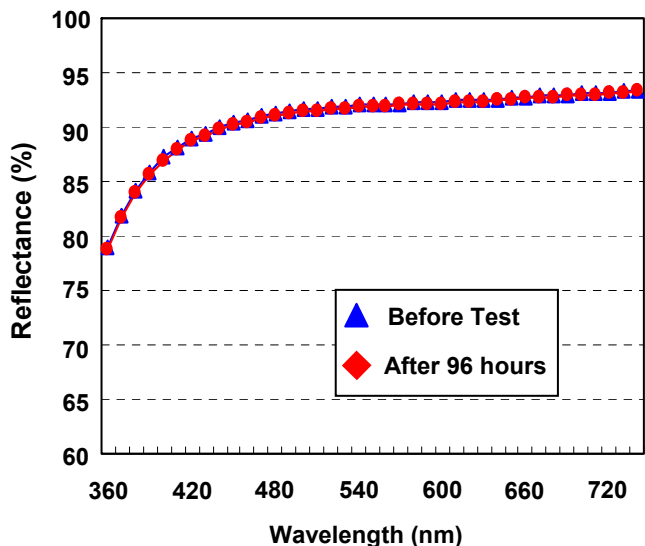
- Equivalent Thermal Conductivity to Alumina
  - Ag Filled Thermal Via  
Thermal Conductivity : 19W / mK
  - More Than 19W / mK Design Available
- High Pattern Pitch Accuracy  
Pattern Pitch Tolerance: +/- 0.25%
- **Highly reliable Ag Reflector**
- Cavity Structure for Higher Reflectance

### Structure (Cavity Structure Example)

### Highly Reliable Ag Reflector



### Reflectance after H<sub>2</sub>S Reliability Test



### Thermal Conductivity per Design

Calculated Value (Chip Size: 1mmSQ)			
Via Diameter	0.10mm	0.10mm	0.15mm
Via Alignment			
Thermal Conductivity (W / mK)	19.0	31.1	42.9

Please ask to Kyocera staff about the availability of thermal conductivity more than 42.9W / mK.

### Test Condition

H<sub>2</sub>S : 10ppm      Temperature: 25degC  
Humidity: 75%      Time: 96 hours